Jetson TX2 NX Fuse Specification

Application Note

DA-10246-001_v1.0 | February 2021

Document History

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Version	Date	Description of Change
1.0	February 2, 2021	Initial Release

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Introduction

This application note provides a technical overview of the issues and considerations related to the NVIDIA® Jetson™ TX2 NX fuse specification.

NVIDIA Jetson TX2 NX includes customer/Original Device Manufacturer (ODM)-programmable fuses which are used to store security keys and ODM system design configuration options. Fuses are divided into 2 distinct areas:

- Manufacturing Fuses (for example, security keys, boot options, etc.)
- ODM Field Fuses (for example, defined by ODM software for rollback protection, IDs, etc.)

All fuses default values are Logic 0 when not burned. After they are burned, they represent Logic 1.

Note: Jetson TX2 NX utilizes NVIDIA® Tegra® X2 which is a Parker series system-on-chip (SOC).

System Requirements

Jetson TX2 NX contains all the power and logic to burn the onboard fuses. The system designer does not have to make any provision in their system design.

Fuse Variables

Jetson TX2 NX contains 2 types of fuses for ODM use. Those that configure the device and should be burned during the manufacturing process before the product is released to the end user, and those that may be burned during the lifetime of the product by the ODM for software to use.

An example of each of these is:

- Manufacturing Fuses: Boot Keys, Boot device
- ODM Fuses: Product serial number, date of first use

Manufacturing Fuses

Jetson TX2 NX contains multiple manufacturing fuses that control different items for security and boot. These fuses should be burned during the manufacturing process. After burning all manufacturing fuses, the ODM Production Mode fuse (also known as "Security Mode") must be burned by the ODM on the manufacturing line before the product is shipped to the end user. This fuse acts as a master lock for all the manufacturing fuses. Once burned it locks the values of the other manufacturing fuses. They cannot be burned once the ODM Production Mode fuse has been burned.

Table 1 summarizes available fuse settings and values for each.

Note: All ODM fuses have the value of ZEROs when shipped to a customer.

CAUTION: Burning a fuse (changing the value of a fuse from 0 to 1) is non-reversible. Once a fuse bit is burned (set to 1), you cannot change the fuse value from 1 to 0. For example: A value of 1 (0x0001) can be changed to 3 (0x0011) or 7 (0x0111). It cannot, however, be changed to a value of 4 (0x0100) since bit zero is already burned to 1.

The burning of fuses should be done without a system reset in between different phases of fuse burning.

The eMMC must be powered and pins associated with eMMC should not be driven externally during the fuse burning process if either of the following conditions holds true:

- It is a boot device.
- RPMB provisioning is done on this device along with fuse burning.

Table 1. Manufacturing Fuses

Fuse Name	Description	Bit Length	Note
FUSE_SECURITY_MODE [0]	**ODM Production Mode** Also known as ODM Security Mode. This fuse write-protects all manufacturing device fuses against any further fuse burning and also hides the SBK values. **This fuse must be burned last.**	1	
FUSE_ARM_JTAG_DIS [0]	**Arm JTAG Disable** Disables future use of Arm JTAG debug port. When this fuse is burned, access to the Arm JTAG debug port is permanently disabled.	1	Note 3
FUSE_DEBUG_AUTHENTICATION [4:0]	**Arm Debug Authentication** Provides fine control of Arm debug capabilities. Burning one of these fuses permanently disables the equivalent debug capability: • Bit 0 forces dbgen to 0 • Bit 1 forces niden to 0 • Bit 2 forces spiden to 0 • Bit 3 forces spniden to 0 • Bit 4 forces deviceen to 0	5	Note 3
FUSE_PRIVATE_KEY0 [31:0] /../ FUSE_PRIVATE_KEY3 [31:0]	**Secure Boot Key (SBK)** Stores an ODM-supplied secure boot key for each chip. Used of SBK is dependent on the authentication scheme selected via fuse_boot_security_info. Example: "0xABCDEF" input value will be represented as "0x0000000000000000000000000ABCDEF"	128	Note 1, 3, 4
FUSE_PUBLIC_KEY0 [31:0] /../ FUSE_PUBLIC_KEY7 [31:0]	**Public Key Hash (PKC)** Stores the hash of a public key provided by the ODM. Storing the hash allows to authenticate the full key.	256	Note 3
FUSE_RESERVED_SW [3]	**Skip Boot Device Selection Straps** Ignores the device selection straps and chooses the secondary boot device from the fuses when set.	1	Note 3
FUSE_RESERVED_SW [2:0]	**Boot Device Selection** Identifies the OS image boot device. Enumerated value read by the internal boot ROM.	3	Note 2, 3
FUSE_BOOT_DEVICE_INFO [23:0]	**Boot Device Configuration**	24	Note 2, 3

Fuse Name	Description	Bit Length	Note
	Identifies the OS image boot device configuration. Used in conjunction with the Boot Device Selection to provide its configuration.		
FUSE_BOOT_SECURITY_INFO[5:0]	**Boot Security Info** Bits interpreted with the following mapping: • [1:0] mapped to Secure Boot Authentication Scheme, where 00b: AES-CMAC using SBK 01b: AES-CMAC using SBK 10b: 2048-bit RSA 11b: NIST P-256 Curve ECC • [2] enables encryption using SBK (all firmware images will be encrypted with SBK) • [5:3] reserved	6	Note 3
FUSE_RESERVED_SW[5]	**Watchdog Enable** Used to enable watchdog	1	Note 3
FUSE_CCPLEX_DFD_ACCESS_DISABLE[0]	**CCPLEX Low-Level DFD ACCESS DISABLE** When fuse is burned, low-level hardware debugging for NVIDIA internal diagnostics is totally disabled.	1	Note 3
FUSE_KEK00[31:0] FUSE_KEK01[31:0] FUSE_KEK02[31:0] FUSE_KEK03[31:0] FUSE_KEK10[31:0] FUSE_KEK11[31:0] FUSE_KEK12[31:0] FUSE_KEK13[31:0] FUSE_KEK20[31:0] FUSE_KEK21[31:0] FUSE_KEK22[31:0] FUSE_KEK23[31:0]	**Key Encryption Key or Key Seed** These 12 consecutive registers can be used to encode some Key Encryption Key and/or some Key Seed, with different combinations of width. Software interprets them as the following: KEK0 (128), KEK1 (128) and KEK2 (128). KEK256 (256-bit key) can be used as a 256-bit key-encryption key; or, as a 128-bit key-encryption key (KEK0) and a 128-bit key generation key (KEK1)	384	Note 3
FUSE_ODM_INFO[15:0]	**ODM Info** 8 LSB contain the 8 LSB of the USB PID for an USB device used for dead battery boot compliance. Bit 14 and Bit 15 are reserved for use by NVIDIA. Remaining bits are reserved for use by ODM.	16	Note 3
FUSE_ODM_CRC[8:0]	**ODM CRC** The 8 LSB are a CRC used to check integrity of a subset of ODM burned information, the MSB is a	9	Note 3, 5

Fuse Name	Description	Bit Length	Note
	present/valid bit (cannot rely on CRC being not zero to indicate CRC is present).The use of a CRC is optional.		
FUSE_ODMID0[31:0] FUSE_ODMID1[31:0]	**ODM ID** These 2 consecutive registers encode a 64-bit ODM ID.	64	Note 3
FUSE_H2	**Hamming Code** Implement the ECC for the ODM manufacturing fuses. **This fuse must be burned just before burning ODM Production Mode.**	14	Note 3, 5, 6

Notes:

1. The SBK is not active to encrypt objects such as the boot loader, CFG, etc. until the ODM Production Mode fuse is burned. Even if these entries are non-zero, the value is valid and can be read back (for example, used for SSK calculation). After ODM production fuse is burned and a subsequent reset, the SBK value cannot be read back.
2. See the boot options fuse configuration table for the correct Boot settings for your platform.
3. Fuse burning of ODM manufacturing fuses is disabled when ODM Production Mode fuse = 1.
4. After burning the value and rebooting the chip, the value is an input to the SSK calculation regardless of whether the ODM Production Mode fuse has been set.
5. Burning of these fuses will be done by NVIDIA software.
6. Check secure boot software package for fuse burning operation.

ODM Production Fuse

The ODM production fuse is a global lock of all the manufacturing fuses. During the manufacturing process, software should burn all other manufacturing fuses, then update the Hamming ECC field (FUSE_H2), then burn the ODM production fuse last.

Arm Architectural Debug

There are two fuses which impact the ability to debug Arm processors in Tegra X2 SoC.

ARM_JTAG_DISABLE

When burned, this fuse permanently prevents any JTAG access to the debug access port that occurs through the JTAG pins on Tegra X2 SoC. This prevents any JTAG access by external Arm debuggers during normal product lifetime.

Note: JTAG is not supported in Jetson TX2 NX.

Arm Debug Authentication Signals

These fuses control the standard Arm debug authentication signals; each fuse forces the corresponding signal to 0 (disabled). Table 2 describes the Arm debug authentication signals.

Table 2. Arm Debug Authentication Signals

Signal Name	Description	Definition	Common Use Case
DBGEN	**Debug Enable** When asserted, enables invasive and non-invasive debug of non-secure state. Note that when DBGEN is not asserted access to debug components is generally still permitted, but those components are disabled.	NonSecure Invasive Debug Enable	CPUs to halt AXIAP to make system accesses ETR to stream trace to DRAM
NIDEN	**Non-Invasive Debug Enable** When asserted, enables non-invasive debug operations, such as trace, of non-secure state. NIDEN can be asserted independently of DBGEN.	NonSecure Non-Invasive Debug Enable	PTM trace from CPUs
SPIDEN	**Secure Privileged Invasive Debug Enable** When asserted along with DBGEN, enables invasive and non-invasive debug of Secure state.	Secure Invasive Debug Enable	AXI_AP to make secure accesses into the system ETR to write to Secure DRAM
SPNIDEN	**Secure Privileged Non-Invasive Debug Enable** When asserted along with NIDEN, enables non-invasive debug of Secure state.	Secure Non-Invasive Debug Enable	Accessing Secure registers in PMU and CPUs over the Debug APB
DEVICEEN	**Device Debug Enabled** Enables the external debug tools connection to the device. This signal also drives the DBGSWENABLE which is an enable input signal of the CoreSight Components and Cortex-A Series processor.	Device Enable	Accessing any registers on mapped over the Debug APB

CCPLEX_DFD_ACCESS_DISABLE

When this fuse is burned (to a 1), NVIDIA internal CCPLEX debug access is disabled on the chip. Burning this fuse will prevent NVIDIA from performing any hardware level debug on the CCPLEX, should it be required.

Secure Boot Key

These fuses should be burned with the secure boot key if SBK is being used. The SBK only takes effect once the ODM Production Mode fuse has been burned.

Public Key Hash

These fuses should be burned with the hash of the ODM public key. It only takes effect once the ODM Production Mode fuse has been burned.

Skip Boot Device Selection Straps

This fuse determines if the boot device selection is determined by the straps or by the fuse settings.

Jetson TX2 NX is supplied as configured to boot from straps. It is recommended that for production devices the fuses are used to select the boot device and this fuse should be burned. When this fuse is burned then the boot device is determined by the setting of the boot device selection fuses.

Boot Device Selection

Jetson TX2 NX uses eMMC for boot. These fuses should remain at their default (0x0 = eMMC).

Table 3. Boot Selection (FUSE_RESERVED_SW[2:0])

Register	Description	Values
FUSE_RESERVED_SW[2:0]	Boot Device Select	0x0 = eMMC

Boot Device Information

These fuses determine parameters for the boot device. Jetson TX2 NX uses eMMC for boot. These fuses should be burned to 0x0020 (512 Byte Page size, 25.5 MHz, Boot Mode Off, Query Voltage, No DDR) if boot fuses are to be burned.

Table 4. Boot Device Configuration eMMC Only

Device	Fuse Bits	Description	Values (Default = 0x0)
eMMC	23:6	Reserved	Ignored; set to 0x0
	5	MultiPage support	0x0 = default Multi page read (page size determined by data length and DMA capability, target memory/buffer size/limits)

Device	Fuse Bits	Description	Values (Default = 0x0)
			0x1 = Single page read (512 Byte)
	4:3	Clock Divider PLLP clock at 408 MHz	0x0 = default clock divider 16 (clock at 25.5 MHz)
			0x1 = clock divider 8 (clock at 51 MHz)
			0x2 = Reserved
			0x3 = Reserved
	2	Disable Boot Mode	0x0 = Boot mode Off
			0x1 = Boot mode On
	1	Voltage Range	0x0 = Query voltage
			0x1 = Low voltage
	0	DDR Mode Selection	0x0 = Normal
			0x1 = DDR

ECC

Individual fuses can fail with very low probability and the fuse logic corrects these failures by using redundancy techniques:

- An OR-ECC, where two fuses are ORed together to get the corrected value. This code is unidirectional and protects against a 1b becoming a 0b.
- A Hamming ECC applied to a set of fuses is able to correct one error in the set of protected fuses. The Hamming code has much less overhead than the OR-ECC but requires groups of bits to be burned together.

Both ECC methods are transparent to software when using fuse option registers to get access to fuse information but requires some care when burning fuses.

ODM Fuses - Field Programmable

The following fuses are available for the system designer to use for burning during the product lifetime. If these fuses are to be altered, then the fuse burning voltage VPP_FUSE must be present in the system at the time the fuses are to be burned.

The RESERVED_ODM fuses are split into 8 banks of 32 bits. The first 4 banks (0-3) can be locked out by setting the corresponding bit in the ODM Lock fuse (for example, to lock RESERVED_ODM Bank 1, then ODM LOCK Bit [1] should be set). This will prevent any unintentional burning of other bits in this bank.

RESERVED_ODM Banks 4-7 do not have this lock feature.

Table 5. ODM Fuses

Fuse Name	Fuse Description	Bit Length
Reserved ODM (FUSE_RESERVED_ODM0 [31:0]) /../ (FUSE_RESERVED_ODM7 [31:0])	Customer programmable fuses. One anticipated application of the Reserved ODM fuses is software version revocation, although their use is solely at the discretion of the customer. The Reserved ODM fuses remain programmable after the ODM Production Mode fuse has been burned. Default value is set to all zeros for Reserved ODM fuses not burned.	256
ODM_lock (FUSE_ODM_LOCK [3:0])	ODM_lock[i] disables further change to the i-th 32 bits subset of the reserved ODM field. Applicable to the first four subsets only. FUSE_ODM_LOCK [0] = Reserved ODM[0] FUSE_ODM_LOCK [1] = Reserved ODM[1] FUSE_ODM_LOCK [2] = Reserved ODM[2] FUSE_ODM_LOCK [3] = Reserved ODM[3]	4

Note: Refer to *Jetson Platform Fuse Burning and Secure Boot Documentation and Tools* for information on how to burn the fuses.

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